Greetings from CMTI

We are pleased to inform you that we are conducting a 03 day Non-Residential Training programme on **"Semiconductor Packaging and Characterization Processes", course code: 3104**

Highlights / Overview of the Program:

- Packaging Fundamentals
- In-depth Understanding of Packaging and Characterization Techniques
- Selection of Packaging Method and Characterization Techniques and their applications
- Future Trends for Industry-Relevant Applications.
- Basic and Advanced semiconductor Packaging Flow, Electrical, Mechanical, Material Characterization.

Target Participants:

Research Students, Scientists, Engineers, Faculty Working in the domain of semiconductor and MEMS Technology.

Programme Schedule

It is 03 day Non Residential Training Programme scheduled during **18th – 20th November 2026, now postponed to future dates.** The Programme will be held at Central Manufacturing Technology Institute, Bengaluru.

Participation Fees

Rs. 11,700/- plus GST @ 18%, per participant. This includes Course Kit, working veg lunch, mid session Tea.**

Course Fee can be paid through **NEFT / RTGS / Demand Draft.** Demand Draft to be drawn in favor of "Central Manufacturing Technology Institute", payable at Bangalore and should reach CMTI one week before the actual date of commencement of the course.

Beneficiary for RTGS/NEFT

a) **Name** : **Central Manufacturing Technology Institute**
b) **GST No: 29AAATC2085K1ZJ**
c) **Account No :10521862015**
d) **Bank Name & Branch: State Bank of India, Yeshwanthpur Branch**
e) **IFSC Code :SBIN0003297**
f) **MICR Code : 560002055**

Additional Information:

1. A 10% rebate on course fee will be given to organizations nominating 3 or more participants for each programme, only if payment is made in advance, ten days before the commencement of the course.
2. Individuals/ Companies interested in participation are requested to fill in the enclosed Enrollment Form and submit at the earliest.
3. Participants are advised to proceed for the programme only after the nominations / Programme confirmed by us (by Fax / Letter / Phone / E-Mail).
4. Participants should report at CMTI on the day of commencement of the course. Participants are advised to reach Bangalore the previous day evening/ night.
5. Course will be conducted from 09:00 to17:00 hrs. Participants may plan their return journey accordingly.
6. Participants will be given Certificate after the completion of the Training Programme
7. Enclosed are the tentative programme contents for ready reference
8. GST No. to be shared while sending your nomination / Registration (If a company is exempted from GST they have to provide GST Exemption certificate).
9. Please note that Course fee once paid will not be refunded. However, change in nomination will be permitted.

Note: * Taxes and other levies will be charged as per the prevailing rates at the time of Billing**

For further enquiries / registration / nominations, please contact:
Mr. Arun Kumar J G, Joint Director & Centre Head – AEAMT,
09449842686 / 78 Fax: (080) 2337 0428
E-mail– training@cmti.res.in, aravinda@cmti.res.in

CENTRAL MANUFACTURING TECHNOLOGY INSTITUTE

Tumkur Road, Bengaluru 560 022

Training Programme
On
"Semiconductor Packaging and Characterization Processes"

Tentative Programme Schedule

Days	Particulars
Day-1	Introduction to MEMS and Semiconductor Packaging
	Thermal management and packaging materials
	Package sealing
	Packaging inspection and Hermeticity testing
Day-2	Wafer dicing
	Wafer bonding
	Wire bonding and bond testing
	Electronics signal conditioning
Day-3	Characterization techniques (optical, electrical, mechanical)
	Flip-chip bonding
	Lab visit
	Feedback and concluding session

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